



Part Number:		AS4C16M16S-7BCN / AS4C16M16S-6BIN							
Part Weight:		112mg							
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM
1	Substrate	HL832NX / AUS308	32.39	Acrylic Resin	Trade secret	7.69%	2.490791	2.22%	76900
				Phthalcyanine Blue	147-14-8	0.03%	0.009717	0.01%	300
				Organic Pigment	Trade secret	0.03%	0.009717	0.01%	300
				Barium Sulfate	7727-43-7	3.92%	1.269688	1.13%	39200
				Silica	7631-86-9	1.96%	0.634844	0.57%	19600
				Talc	14807-96-6	1.96%	0.634844	0.57%	19600
				Aromatic Carbonyl C	Trade secret	0.75%	0.242925	0.22%	7500
				Amine Compound	Trade secret	0.12%	0.038868	0.03%	1200
				Antifoamer	Trade secret	0.15%	0.048585	0.04%	1500
				Levelling Agent	Trade secret	0.15%	0.048585	0.04%	1500
				Diethylene Glycol Mo	112-15-2	0.03%	0.009717	0.01%	300
				Dipropylene Glycol M	34590-94-8	2.75%	0.890725	0.80%	27500
				3-Methoxy-3-Methyl	1103429-90-9	4.31%	1.396009	1.25%	43100
				Solvent Trade secretp	64742-94-5	0.72%	0.233208	0.21%	7200
				Acrylic Monomer	Trade secret	1.18%	0.382202	0.34%	11800
				Epoxy Resin	90598-46-2	4.01%	1.298839	1.16%	40100
				Organic Filler	Trade secret	0.39%	0.126321	0.11%	3900
				Copper	7440-50-8	5.52%	1.787928	1.60%	55200
				Continuous Filament	65997-17-3	16.55%	5.360545	4.79%	165500
				Bismaleimide	13676-54-5	6.71%	2.173369	1.94%	67100
				Triazine	25722-66-1	6.24%	2.021136	1.80%	62400
				Epoxy Resin	Trade secret	5.76%	1.865664	1.67%	57600
				Inorganic filler	Trade secret	7.19%	2.328841	2.08%	71900
Copper plating	7440-50-8	17.90%	5.79781	5.18%	179000				
Nickel plating	7440-02-0	3.45%	1.117455	1.00%	34500				
Gold plating	7440-57-5	0.53%	0.171667	0.15%	5300				
2	Solder ball	M705	19.031	Sn	7440-31-5	96.50%	18.364915	16.40%	965000
				Ag	7440-22-4	3.00%	0.57093	0.51%	30000
				Cu	7440-50-8	0.50%	0.095155	0.08%	5000
3	Mold compound	KE-G1250	50.602	Silica(Fused)	60676-86-0	88.70%	44.883974	40.07%	887000
				Epoxy resin	Trade Secret	5.50%	2.78311	2.48%	55000
				Phenol resin	Trade Secret	5.50%	2.78311	2.48%	55000
				Carbon Black	1333-86-4	0.30%	0.151806	0.14%	3000
4	Epoxy	2025D	1.039	Silica, amorphous, tre	68909-20-6	33.95%	0.3527405	0.31%	339500
				Silicon dioxide	7631-86-9	20.00%	0.2078	0.19%	200000
				Acrylate monomer	Trade Secret	7.50%	0.077925	0.07%	75000
				2,6-Diglycidyl phenyl	Trade Secret	7.50%	0.077925	0.07%	75000
				Bismaleimide monom	Trade Secret	20.00%	0.2078	0.19%	200000
				Additive	Trade Secret	7.50%	0.077925	0.07%	75000
				Methacrylate resin	Trade Secret	3.00%	0.03117	0.03%	30000
				2-Ethyl-4-methyl-1H-	23996-25-0	0.55%	0.0057145	0.01%	5500
5	Gold wire	Au	0.894	Gold	7440-57-5	99.05%	0.88548912	0.79%	990480
				Palladium	7440-05-3	0.95%	0.008493	0.01%	9500
				Calcium	7440-70-2	0.00%	0.00001788	0.00%	20
6	Die	Chip	8.044	Silicon	7440-21-3	100.00%	8.044	7.18%	1000000

112

600.00%

112

100.00%

6000000